TOSHIBA SG1000GXH26

TOSHIBA GATE TURN-OFF THYRISTOR LOW SNUBBER TYPE

SG1000GXH26

INVERTER APPLICATION

Repetitive Peak Off-State Voltage $: V_{DRM} = 4500 V$

R.M.S. On-State Current : $I_{T (RMS)} = 500 A$

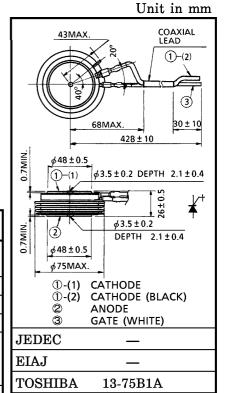
Peak Turn-Off Current : $I_{TGQM} = 1000 A$

Critical Rate of Rise of On-State Current : $di/dt = 600 \text{ A}/\mu\text{s}$

Critical Rate of Rise of Off-State Voltage : $dv/dt = 1000 V/\mu s$

MAXIMUM RATINGS

CHARACTERISTIC	SYMBOL	RATING	UNIT
Repetitive Peak Off-state Voltage (Note 1)	$v_{ m DRM}$	4500	V
Repetitive Peak Reverse Voltage	v_{RRM}	16	V
Peak Turn-Off Current (Note 2)	ITGQM	1000	A
R.M.S. On-State Current (Note 3)	I _T (RMS)	500	A
Peak One Cycle Surge On-State Current (Non Repetitive, 10 ms- Width Half Sine Waveform)	I_{TSM}	8000	A
Critical Rate Of Rise Of On-State Current (Note 4)	di / dt	600	A/μs
Peak Gate Current	I_{GM}	450	A
Average Gate Power Dissipation	P _G (AV)	80	W
R.M.S Gate Current (Note 5)	I _G (RMS)	42	A
Peak Reverse Gate Voltage (at Static)	V _{RGM} 16		V
Operating Junction Temperature Range	Tj	-40~125	°C
Storage Temperature Range	T _{stg} -40~150		°C
Mounting Force	_	13.7 ± 1.4	kN



Weight: 520 g

(Note 1) : $V_{GK} \le -2 \, V$ (Note 2) : $V_{DM} \le 4000 \, V$, $C_S \ge 0.7 \, \mu F$, $di_{GQ} / dt \ge 25 \, A / \, \mu s$, $L_S \le 0.2 \, \mu H$ ($V_{DSP} \le 900 \, V$) (Note 3) : $50 \, Hz$ Half Sine Waveform at $T_f \le 83^{\circ} C$

(Note 4): $V_D \le 2250 \text{ V}, I_{GM} \ge 20 \text{ A} (t_r \le 1 \mu \text{s})$

(Note 5): Ambient Temperature of coaxial gate and cathode lead ≤ 90°C

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ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	TEST CONDITION		MIN	TYP.	MAX	UNIT
Repetitive Peak Off-state Current	I _{DRM}	$V_{ m DRM} = 4500 m V, V_{ m GK} = -2 m V, \ T_i = 125 m C$		_	_	40	mA
Repetitive Peak Reverse Current	I_{RRM}	$V_{ m RRM} = 16 \ m V, \ T_j = 125 m ^{\circ} C$		_	_	10	mA
Repetitive Peak Reverse Gate Current	$I_{ m RGM}$	$V_{ m RGM} = 16 \ m V, \ T_j = 125 m ^{\circ} C$		_	_	10	mA
Peak On-State Voltage	$V_{ extbf{TM}}$	$I_{TM} = 1000 \text{ A}, T_j = 125 ^{\circ}\text{C}$		_	_	4.0	V
Gate Trigger Voltage	v_{GT}	$V_D = 24 V$,	$T_j = -40^{\circ}C$	_	_	1.7	V
			$T_j = 25^{\circ}C$	_	_	1.0	V
Gate Trigger Current	I_{GT}	$R_{\rm L} = 0.1 \Omega$	$T_j = -40^{\circ}C$	_	_	6.0	A
			$T_j = 25^{\circ}C$	_	_	2.0	A
Turn-On Delay Time	$t_{ m d}$	$V_D = 2250 \text{ V}, I_T = 1000 \text{ A},$ $di / dt = 600 \text{ A} / \mu \text{s},$		_	_	3.0	μ s
Turn-On Time	$\mathbf{t}_{ ext{gt}}$	$egin{aligned} ext{I}_{ ext{GM}} &= 20 ext{ A (t}_{ ext{r}} = 1 \ \mu ext{s),} \ ext{T}_{ ext{j}} &= 25 ^{\circ} ext{C} \end{aligned}$		_	_	10.0	μs
Critical Rate Of Rise Of Off- State Voltage	dv/dt	$V_{DRM} = 3000 \text{ V}, V_{GK} = -2 \text{ V},$ Exponential Rise, $T_j = 125^{\circ}\text{C}$		1000	_	_	V/μs
Storage Time	t_{s}	$I_{TGQ} = 1000 A, V_D = 2250 V, \ V_{DM} = 4000 V, \ Cs = 0.7 \mu F, T_j = 125 ^{\circ} C, \ di_{GQ} / dt = 25 A / \mu s, \ Off Squeeze Current \geq 500 mA$		_	_	17	μ s
Gate Turn-Off Time	${ m t_{gq}}$			_	_	19	μs
Gate Turn-Off Current	I_{GQ}			_	350	_	Α
Tail Time	t _{tail}			_	_	40	μ s
Thermal Resistance (Junction to Fin)	R _{th (j-f)}	DC		_	_	0.028	°C/W

